L Number	Hits	Search Text	DB	Time stamp
1	1	reinforced adj semiconductor adj	USPAT;	2003/11/15 11:38
		interconnect adj structure	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	3	uninformed add interconnect add atmosture	IBM_TDB USPAT;	2003/11/15 11:40
2	3	reinforced adj interconnect adj structure	US-PGPUB;	2003/11/13 11:40
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
3	15	reinforced adj interconnect	USPAT;	2003/11/15 11:41
			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
4	72	reinforced adj via	USPAT;	2003/11/15 11:43
4	12	Telliforced adj via	US-PGPUB;	2003/11/13 11.43
		·	EPO; JPO;	
	'		DERWENT;	
			IBM_TDB	
5	56	reinforced adj plug	USPAT;	2003/11/15 11:44
1			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
6	7	reinforced adj semiconductor adj (device	USPAT;	2003/11/15 11:45
	,	or structure or portion or element)	US-PGPUB;	2000, 11, 10 11.10
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	, _ ,
7	39	reinforced adj semiconductor	USPAT;	2003/11/15 11:46
			US-PGPUB; EPO; JPO;	
			DERWENT;	`
			IBM TDB	
8	638	semiconductor adj supports	USPAT;	2003/11/15 11:46
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
9	73	semiconductor adi support adi strusturos	IBM_TDB USPAT;	2003/11/15 11:48
9	/3	semiconductor adj support adj structures	US-PGPUB;	2003/11/13 11:40
:			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
10	9	semiconductor adj support adj elements	USPAT;	2003/11/15 11:49
			US-PGPUB;	
	1		EPO; JPO; DERWENT;	
			IBM TDB	
11	7	semiconductor adj support adj (region or	USPAT;	2003/11/15 11:49
	<u> </u>	area or potion)	US-PGPUB;	
			EPO; JPO;	
1			DERWENT;	
			IBM_TDB	2002/11/15 11 51
12	11	semiconductor adj support adj (region or	USPAT;	2003/11/15 11:51
		area or portion)	US-PGPUB; EPO; JPO;	
	1		DERWENT;	
			IBM_TDB	
13	150	(multilevel adj metallization) and	USPĀT;	2003/11/15 12:00
		(supports or reinforcements)	US-PGPUB;	
	1		EPO; JPO;	
			DERWENT;	
14	= -	(plurality add motallization) and	IBM_TDB USPAT;	2003/11/15 12:10
14	56	(plurality adj metallization) and (supports or reinforcements)	US-PGPUB;	2003/11/13 12.10
	1	(Supports of Total October 1997)	EPO; JPO;	
	•		DERWENT;	
			IBM TDB	
		· · · · · · · · · · · · · · · · · · ·		

15	202	(plurality adj metal adj (layers or	USPAT;	2003/11/15 12:13
13	202	films)) and (supports or reinforcements)	US-PGPUB;	2003/11/10 10:13
		lilimo,, and (pappores of reinforcement)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
16	45	(first adj metal adj interconnect) and	USPAT;	2003/11/15 12:16
10	10	(supports or reinforcements)	US-PGPUB;	
		(ouppoint of formeror)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
17	283	first adj metal adj interconnect	USPAT;	2003/11/15 12:21
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
18	62	plurality adj metal adj interconnect	USPAT;	2003/11/15 12:22
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
19	36	multiple adj metal adj interconnect	USPAT;	2003/11/15 12:24
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
20	87	multilevel adj metal adj interconnect	USPAT;	2003/11/15 12:24
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	